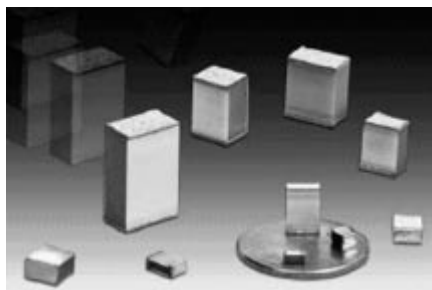


Type FCN Material Content Declaration 1206 and 1210

Stacked Metallized Film (PEN) Chips for Reflow Soldering

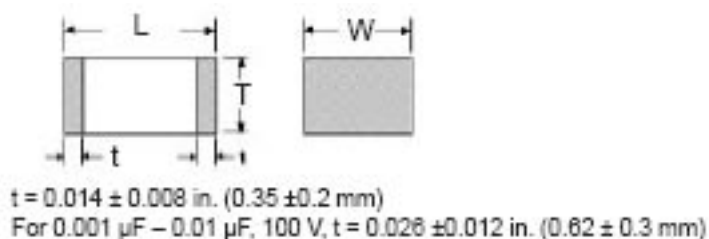


Material Content for RoHS Compliant Parts

Construction Element	Material Group	Materials	CAS if Applicable	Typical Mass (Wt. %)	ppm	Sum (%)
Active Part	Metals	Al (metal spray)	7429-90-5	.7	7000	37.2
	Polymers	PEN	25853-85-4	36.5	365000	
Termination	Metals	Cu/Zn (metal spray)		46.9	469000	62.8
	Metals	CuNi/Ag		11.3	113000	
	Polymers	Phenol Resin	9003-35-4	1.0	10000	
	Metal	Sn/Ag/Cu (Plating)		3.6	36000	
					Total	100.0

Case Sizes, Weight and Outline Drawing

Case Size LxW (mm)	Weight (mg)
1206	15.1 - 20.1
1210	32.2 - 45.1



061506

To the best of our knowledge, the information provided on the enclosed is correct as of the date indicated on the document. Since some of the information is provided by the acceptance of data from sources outside of Cornell Dubilier Electronics, we can not guarantee that all is complete and accurate.